

CLAIMS

What is claimed is:

1. A package semiconductor product comprising:
a base substrate;
a plurality of semiconductor dies;
an RF transceiver on at least two of the semiconductor dies each of said RF transceivers providing a communication capability with at least one other one of said RF transceivers, and each RF transceiver operatively connected to circuitry on its respective die, wherein the dies having the RF transceivers communicate with at least one other die having said communication capability.
2. The package semiconductor product of claim 1 further comprising the dies positioned in a vertically stacked relationship, with one of said dies in an adjacent relationship with the base substrate.
3. The package semiconductor product of claim 1 wherein at least one of said semiconductor dies includes a hardwire signal connection with the substrate, and at least one other die uses an RF transceiver to communicate with the die having the hardwire connection and thereby establishes a signal to the substrate through the RF transceiver.
4. The semiconductor packaged product of claim 1 further comprising at least two of the semiconductor dies having RF transceivers connected directly to the base substrate.